



SOT1134-2

plastic compatible thermal enhanced extremely thin quad flat package; no leads

10 June 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HXQFN60U
Package type industry code	HXQFN60U
Package style descriptive code	HXQFN (thermal enhanced extremely thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	22-8-2011

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	3.9	-	4	4.1	mm
E	package width	5.9	-	6	6.1	mm
A	seated height	-	-	-	0.5	mm
A ₂	package height	0.38	-	0.4	0.42	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	60	-	



2. Package outline

**HXQFN60: plastic compatible thermal enhanced extremely thin quad flat package; no leads;
60 terminals; body 4 x 6 x 0.5 mm**

SOT1134-2

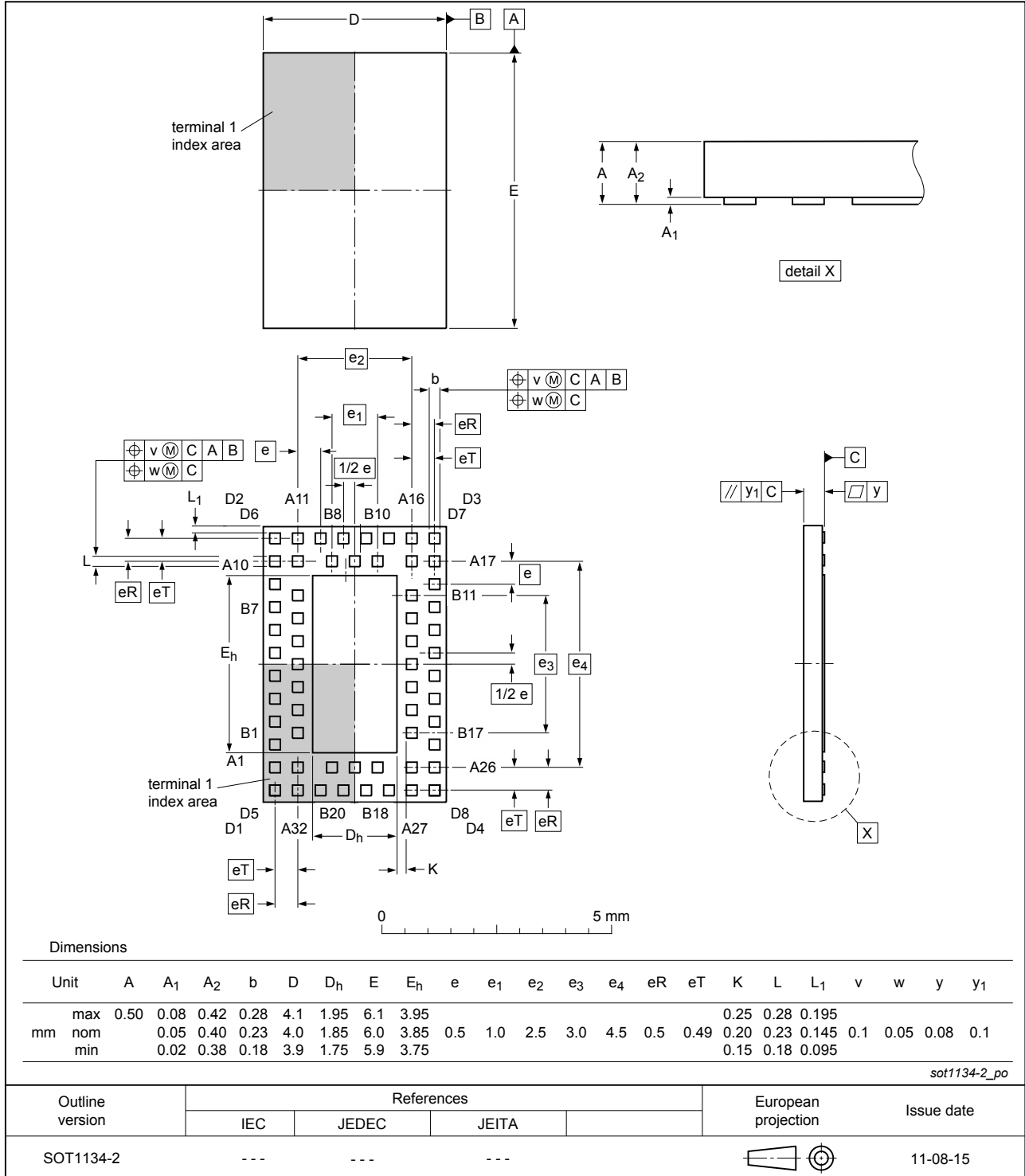


Fig. 1. Package outline HXQFN60U (SOT1134-2)

3. Soldering

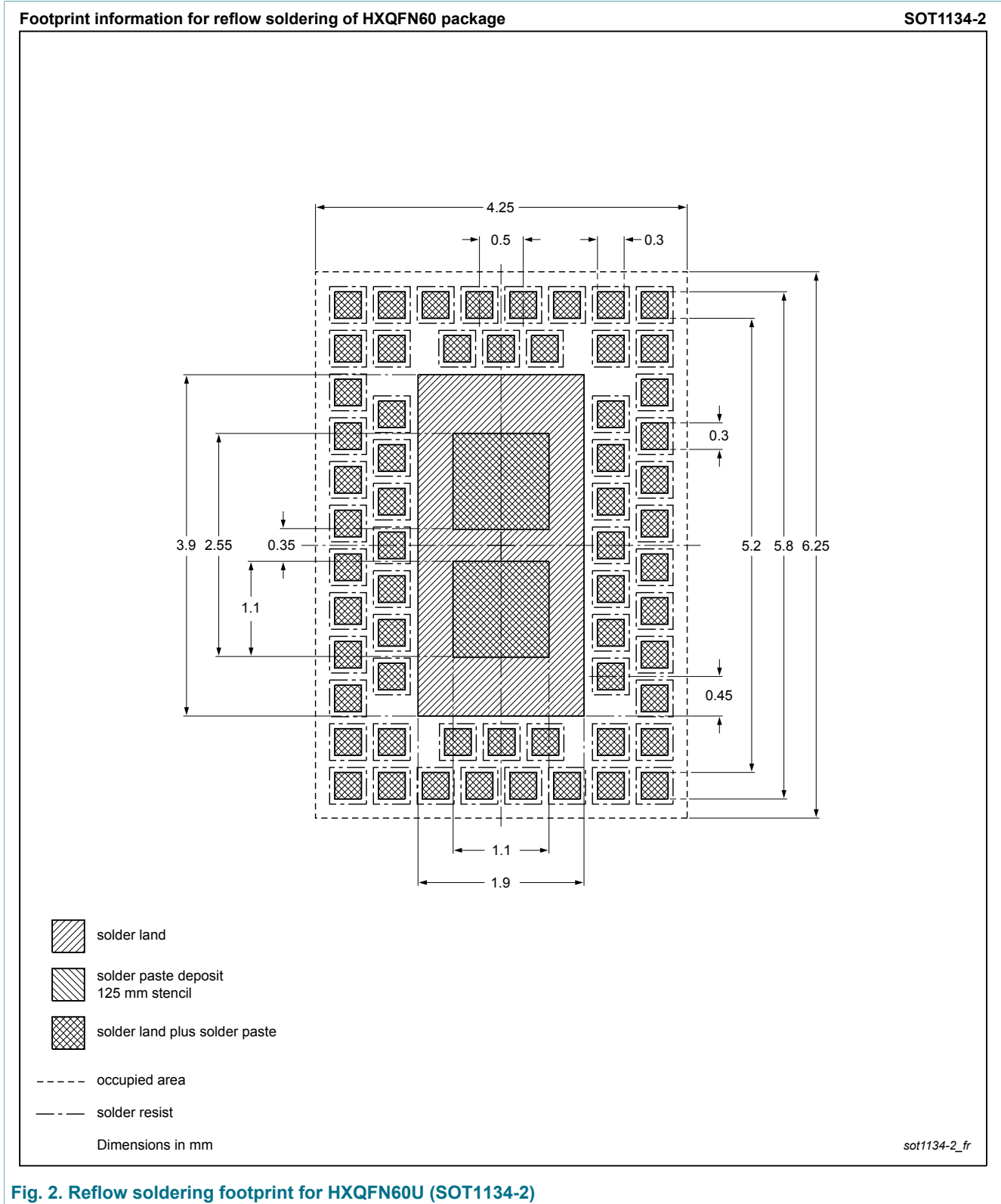


Fig. 2. Reflow soldering footprint for HXQFN60U (SOT1134-2)

4. Legal information

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